

Title (en)

PIEZOELECTRIC PRESSURE SENSING APPARATUS FOR INTEGRATED CIRCUIT TESTING STATIONS

Publication

EP 0259942 A3 19891004 (EN)

Application

EP 87302425 A 19870320

Priority

US 90535886 A 19860908

Abstract (en)

[origin: US4673839A] A pressure sensing apparatus for use in an integrated circuit testing station is disclosed. The testing station includes a probe, a support structure, and lift means for moving an integrated circuit upward toward the probe. The invention specifically consists of a pressure pad secured to the support structure directly above the probe. The pad includes a resilient body portion having a rigid tip. Embedded within the pad is a piezoelectric element having electrical contact leads attached thereto. When the testing station is used, an integrated circuit is moved upward by the lift means toward the probe. As the circuit contacts the probe, it moves the probe upward. As the probe moves upward, it pushes on the pad, causing internal pressures to be generated therein. Such pressures are transmitted to the piezoelectric element which generates electrical impulses proportional to the pressures exerted on the pad.

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G01R 31/28

IPC 8 full level

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H01L 21/00 (2013.01 - KR)

Citation (search report)

- [Y] US 4195259 A 19800325 - RATLIFF CHARLES R [US], et al
- [Y] IBM TECHNICAL DISCLOSURE BULLETIN

Cited by

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